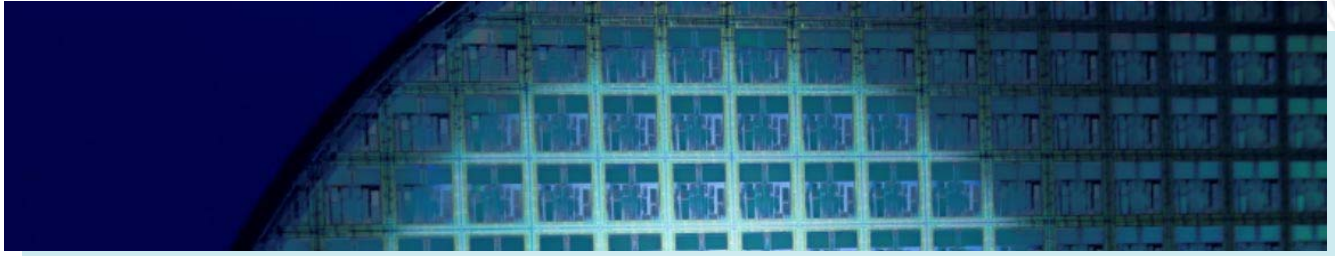


BPS-729-B



SURFACTANT-FORMULATED DICING SOLUTION



BPS-729-B surfactant-formulated dicing solution is used as an additive to DIW during the dicing process for high-performance cleaning through superior wetting. In addition to preventing adherence of silicon particles and swarf (saw residue) on Al and Cu substrates, this product can also remove oxidation from bond pads. Because of the very low etch rate on various base materials, these substrates are not affected.

BPS-729-B surfactant-formulated dicing solution is recommended for use between 500:1 and 2000:1 for standard dicing application, and at stronger concentrations for Copper Oxide removal applications.

Treatment is typically followed by a DI water rinse and dry as is normally performed within the dicing machine or on a standalone tool.

BENEFITS

Room temperature application
Does not attack the base metal
Works on Cu, Al, Sn, among others
Eliminates the need for scrubbing the wafer post-saw
Eliminates the need for CO ₂ sparged DIW
High conductivity even at high dilutions which helps to dissipate electrostatic charge on ESD-sensitive devices
surface tension even at high dilutions which promotes excellent swarf and particle removal
Removes oxides that lead to poor wire bonding

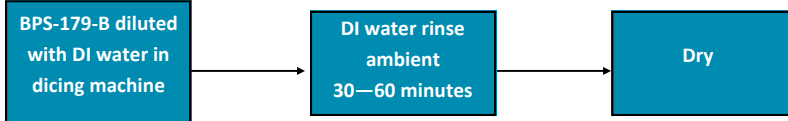
TYPICAL PHYSICAL PROPERTIES

Form:	Liquid
Color:	Clear
Density:	64.301 lb/ft ³ (1.03 g/cm ³)
pH	5.5-6.5

MATERIAL COMPATIBILITY

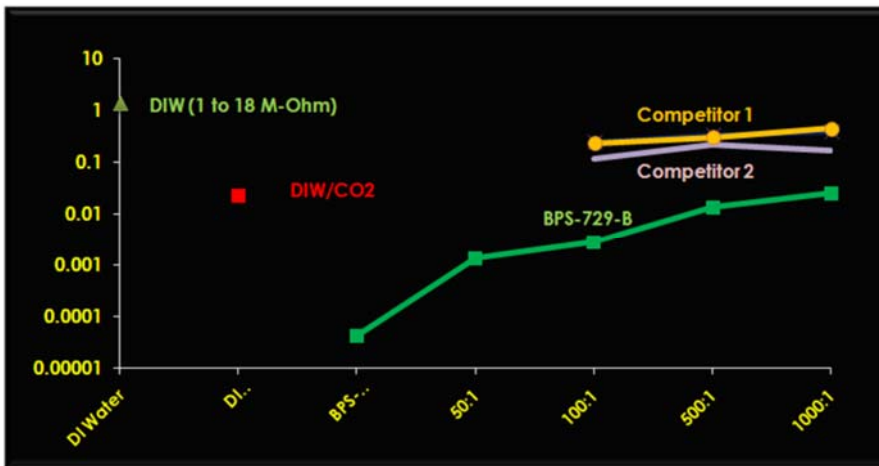
Wetted Parts	O-Rings
High-density polyethylene (HDPE)	FEP Encapsulated Viton
PFA	Kalrez
PTFE	EPR
PVDF	
Polypropylene	
Stainless Steel 316	

INSTRUCTIONS FOR USE



ETCH RATES

MATERIALS	ETCH RATES (Å/MIN) @ 500:1 DILUTION; 25°C
Al	< 1
Cu	< 1
SiN	TBD
TiN	TBD

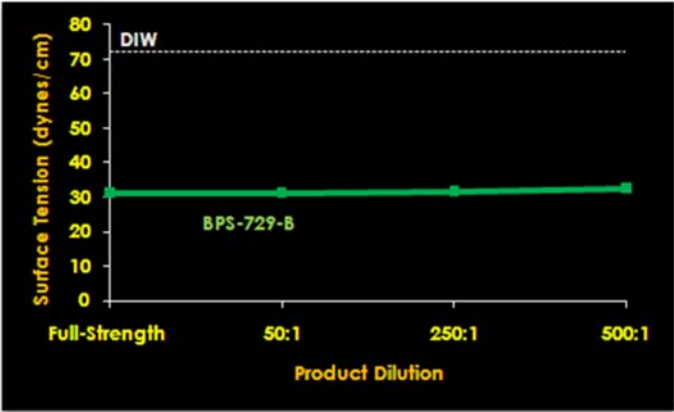


**PERFORMANCE DATA
RESISTIVITY VERSUS DILUTION AGAINST
CO₂-SPARGED DIW AND COMPETITIVE
PRODUCTS**

**BPS-729-B SURFACTANT FORMULATED
DICING SOLUTION REDUCES RESISTIVITY
OF DIW MORE EFFECTIVELY THAN CO₂
AND THE COMPETITION!**

BPS-729-B	
Product Dilution	Surface Tension (dynes/cm)
Full-Strength	31.2
50:1	31.3
250:1	31.8
500:1	32.6
1000:1	34.7

SURFACE TENSION VERSUS DILUTION



THIS PRODUCT REDUCES RESISTIVITY OF DIW MORE EFFECTIVELY THAN CO₂ AND THE COMPETITION!

PH VERSUS DILUTION

DILUTION	PH
No dilution	5.7
50:1	6.4
100:1	6.5
250:1	6.6
500:1	6.6
1000:1	6.6



STANDARD PACKAGING



For more information, please contact us at:

VERSUM MATERIALS, LLC
VERSUMMATERIALS.COM

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